

20-3722

LOW DENSITY EPOXY ADHESIVE/SEALANT

DESCRIPTION:

20-3722 is a low density, two component epoxy bonding and sealing system. The 20-3722 is less than half the weight of most commercially available potting compounds. 20-3722 exhibits very low shrinkage during the cure cycle and also has a low coefficient of thermal expansion. This unique epoxy system is ideal where a low dielectric constant and low weight are required.

This epoxy syntactic foam system utilizes an advanced micro balloon technology filler. The 20-3722 provides high strength and stiffness, thermal and environmental stability, creep resistance, and water resistance.

FEATURES:

- Low Dielectric Constant
- Low Coefficient of Thermal Expansion
- Low Shrinkage
- Low Density
- Excellent Moisture Resistance

TYPICAL SPECIFICATIONS:

Viscosity resin, 25°C, cps	Non-Sag Paste
Specific gravity, @ 25°C	0.82
Pot life, 100 gram mass, @ 25°C	3-4 Hours
Hardness, Shore D	80D
Flexural strength, psi	7,000
Compressive strength, psi	12,000
Tensile strength, psi	3,000
Linear shrinkage, in/in	0.001
Water absorption, % (24 hr.)	0.13
Coefficient of thermal expansion, °C	43x10 ⁻⁶
Thermal conductivity, W/m- °K	0.18
Operating temperature, °C	-60 to +160
Dielectric strength, V/mil	375
Dielectric constant, 1 MHz	2.70
Dissipation factor, 1 MHz	.05
Volume resistivity, ohm-cm @ 25°C	>10 ¹³
Mix ratio by weight (Resin: Catalyst 30)	100:20
Mix ratio by volume	100:17

MIXING INSTRUCTIONS:

With CATALYST 30:

- 1) By weight thoroughly mix 20 parts Catalyst 30 to 100 parts 20-3722 Resin.
 - 2) Apply and cure according to one of the following cure schedules:
 - a) 85°C (185°F) 3-4 hours
 - b) 100°C (212°F) 2-3 hours
- For optimum performance, an additional 2 hours @ 365°F (185°C) is recommended.

IMPORTANT:

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